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Welding and Joining Processes of Materials

Collection Editor:

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Message from the Collection Editor

Dear Colleagues,

Welding and joining processes of materials are key technologies applied to the manufacture of most industrial products such as buildings, bridges, ships, automobiles, aircrafts, pressure vessels, pipelines, electronic equipment, and so on.

The scope of this Special Issue focuses on recent advances in the field of welding and joining processes of materials. The topics of interest include but are not limited to the following:

- Developments of advanced welding and joining processes;
- Modelling and simulation of welding and joining processes;
- Heat source properties;
- Heat source–material interaction mechanism;
- Fluid mechanics and heat transfer in weld pools.

We would like to invite you to submit original research articles and reviews related to any topics mentioned above.

Dr. Shinichi Tashiro
Guest Editor



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Message from the Editor-in-Chief

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